



**DDR3 DIMM, DDR3 SO DIMM**

TE Internal #: 1932680-2

TE Internal Description: VLP DDR3 DIMM 240POS. 1.0PITCH

DDR3 DIMM Sockets

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Connectors > Socket Connectors > Memory Sockets > DIMM Sockets > DDR3 DIMM Sockets



DRAM Type: **Double Data Rate (DDR) 3**

Connector System: **Board-to-Board**

Number of Positions: **240**

PCB Mounting Style: **Through Hole - Solder**

Module Orientation: **Vertical**

[All DDR3 DIMM Sockets \(13\)](#)

## Features

### Product Type Features

DRAM Type	Double Data Rate (DDR) 3
Connector System	Board-to-Board
Connector & Contact Terminates To	Printed Circuit Board

### Configuration Features

Number of Bays	2
Number of Keys	1
Number of Rows	2
Number of Positions	240
Module Orientation	Vertical

### Electrical Characteristics

DRAM Voltage	1.5 V
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### Body Features

PCB Retention Feature Material	Copper Alloy
Ejector Material Color	Black
Ejector Material	Thermoplastic
Latch Color	Black
Ejector Location	Both Ends

Latch Material	Thermoplastic
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Retention Post Location	Both Ends
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Module Key Type	Offset Left
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Ejector Type	Rotary
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### Contact Features

Memory Socket Type	Memory Card
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Socket Style	DIMM
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PCB Contact Termination Area Plating Material Thickness	2.54 $\mu\text{m}$ [100 $\mu\text{in}$ ]
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Contact Mating Area Plating Material Thickness	.51 $\mu\text{m}$ [20 $\mu\text{in}$ ]
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Contact Mating Area Plating Material	Gold
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PCB Contact Termination Area Plating Material	Tin
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Contact Base Material	Copper Alloy
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Contact Current Rating (Max)	.5 A
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### Termination Features

Insertion Style	Direct Insert
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Termination Post & Tail Length	3.18 mm[.125 in]
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### Mechanical Attachment

Mating Alignment Type	Offset Left
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Mating Alignment	Without
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Mount Angle	Vertical
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PCB Mount Retention	With
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PCB Mount Retention Type	Boardlock
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PCB Mounting Style	Through Hole - Solder
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Connector Mounting Type	Board Mount
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### Housing Features

Housing Material	High Temperature Nylon
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Housing Color	Black
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Centerline (Pitch)	2 mm[.07 in]
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### Dimensions

Center Retention Hole Diameter	2.45 mm[.096 in]
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Profile Height from PCB	21 mm[.82 in]
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Row-to-Row Spacing	1.9 mm[.075 in]
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### Usage Conditions

Operating Temperature Range	-40 – 85 °C[-40 – 185 °F]
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### Operation/Application

Circuit Application	Signal
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### Industry Standards

UL Flammability Rating	UL 94V-0
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### Packaging Features

Packaging Quantity	54
Packaging Method	Soft Tray

### Product Compliance

[For compliance documentation, visit the product page on TE.com>](#)

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2022 (224) Candidate List Declared Against: JUN 2020 (209) Does not contain REACH SVHC
Halogen Content	Not Low Halogen - contains Br or Cl > 900 ppm.
Solder Process Capability	Wave solder capable to 260°C

#### Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

Also in the Series | **DDR3 DIMM**



DIMM Sockets(14)

## Also in the Series | **DDR3 SO DIMM**



DIMM Sockets(9)



SO DIMM Sockets(3)

## Documents

### Product Drawings

VLP DDR3 DIMM 240POS. 1.0PITCH

English

### CAD Files

3D PDF

3D

Customer View Model

[ENG\\_CVM\\_CVM\\_1932680-2\\_A1.2d\\_dxf.zip](#)

English

Customer View Model

[ENG\\_CVM\\_CVM\\_1932680-2\\_A1.3d\\_igs.zip](#)

English

Customer View Model

[ENG\\_CVM\\_CVM\\_1932680-2\\_A1.3d\\_stp.zip](#)

English

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### Product Specifications

Product Specification

English